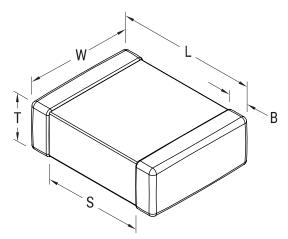


C1206X103M1GEC

ESD SMD Comm COG, Ceramic, 0.01 uF, 20%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Bulk, Bag

1

Packaging Specifications

Packaging Packaging Quantity Specifications Capacitance 0.01 uF **Measurement Condition** 1 kHz 1.0Vrms Tolerance 20% 100 VDC Voltage DC ESD Level per AEC-Q200 25,000 V ESD Level Dielectric Withstanding Voltage 250 VDC **Temperature Range** -55/+125°C Temp. Coefficient COG Capacitance Change with Reference to +25°C and 0 VDC 30 ppm/C, 1kHz 1.0Vrms Applied (TCC) **Dissipation Factor** 0.1%1 kHz 1.0Vrms Aging Rate 0% Loss/Decade Hour Insulation Resistance 100 GOhms

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